

SOT1071-1

plastic very thin fine-pitch ball grid array package; 81 balls

8 February 2016

Package information

1. Package summary

Terminal position code	B (bottom)
Package type descriptive code	VFBGA81
Package type industry code	VFBGA81
Package style descriptive code	VFBGA (very thin fine-pitch ball grid array)
Package style suffix code	NA (not applicable)
Package body material type	P (plastic)
Mounting method type	S (surface mount)
Issue date	8-2-2008

Table 1. Package summary

Symbol	Parameter		Min	Typ	Nom	Max	Unit
D	package length		4.4	-	4.5	4.6	mm
E	package width		4.4	-	4.5	4.6	mm
A	seated height		0.8	-	0.9	1	mm
A ₂	package height		0.65	-	0.7	0.75	mm
n ₂	actual quantity of termination		-	-	81	-	



2. Package outline

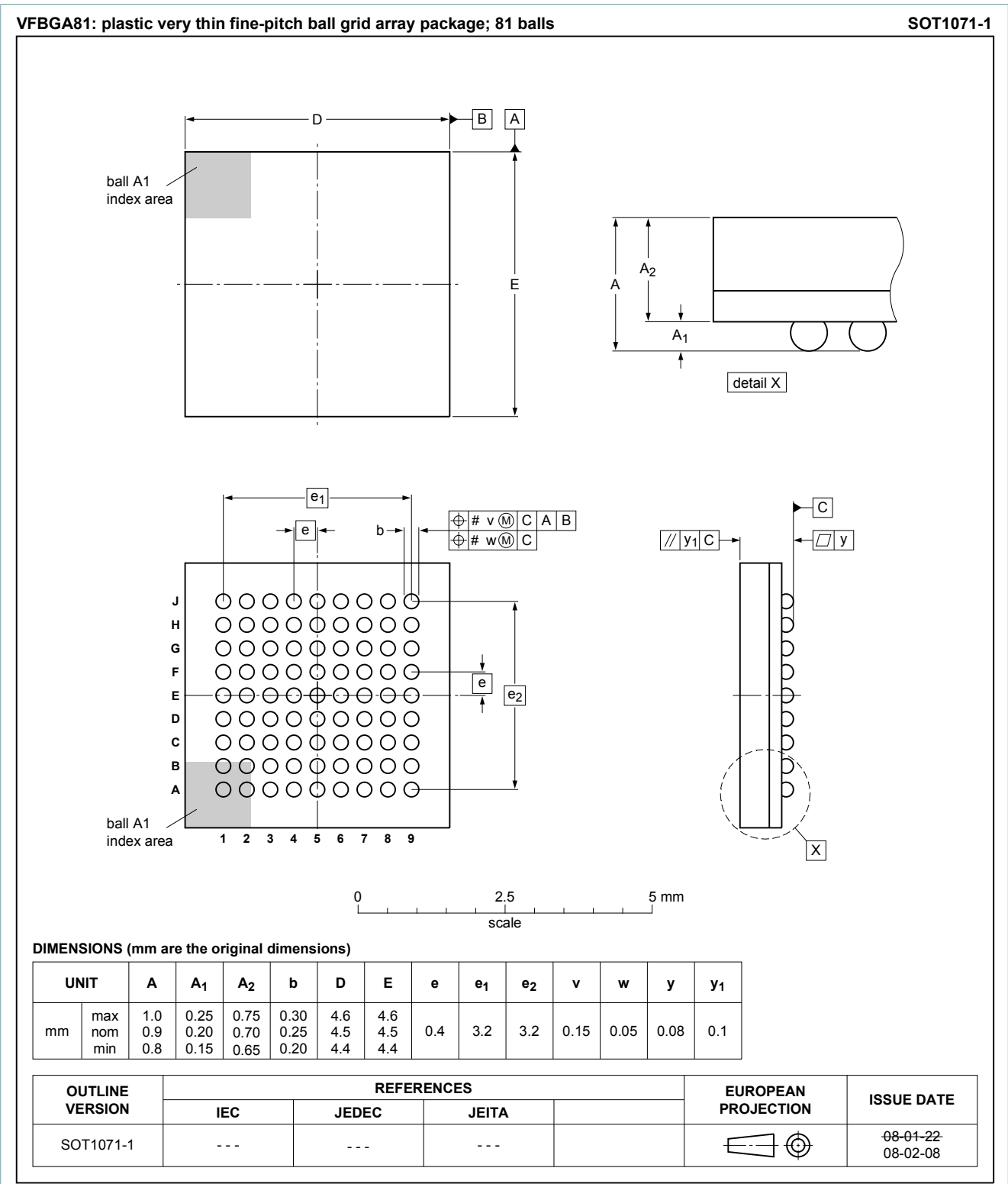


Fig. 1. Package outline VFBGA81 (SOT1071-1)

3. Soldering

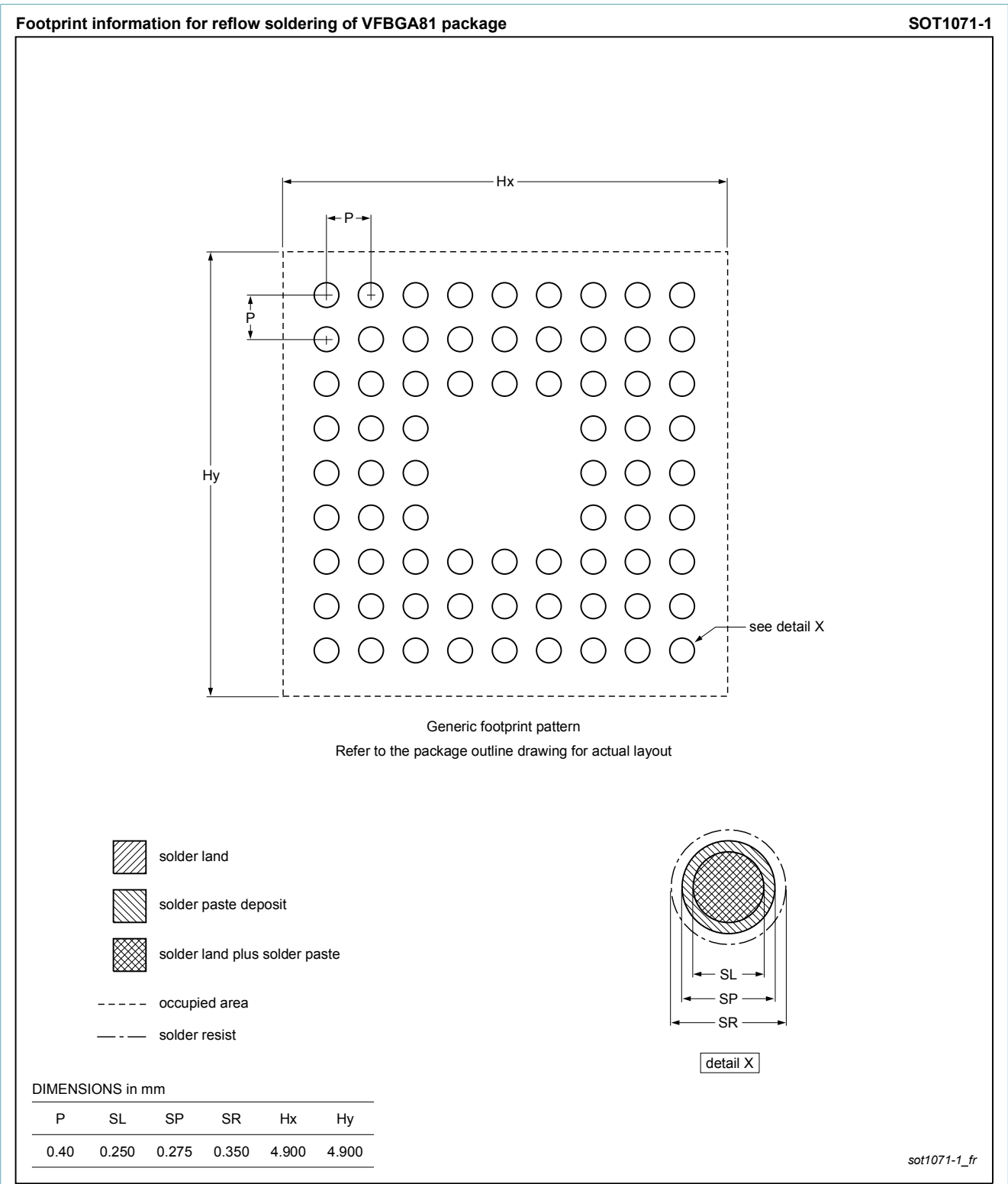


Fig. 2. Reflow soldering footprint for VFBGA81 (SOT1071-1)

4. Legal information

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Date of release: 8 February 2016